In the claims:

Please amend the claims as follows:

1. (Currently Amended) A circuit device manufacturing method comprising ~~the steps of~~:

preparing a conductive foil;

~~forming conductive patterns, by preparing a conductive foil and then forming~~providing in the conductive foil, isolation trenches ~~shallower~~having a depth less than a thickness of the conductive foil~~, on the conductive foil in regions except at least the conductive patterns on which a number of mounting portions of circuit elements are formed~~;

~~covering surfaces of the conductive patterns and the isolation trenches with a resist layer and~~

~~forming~~providing a conductive plating layer on the conduction foil between the isolation trenches, said conductive plating layer being recessed from edges of the conduction foil ~~in desired regions of the conductive patterns~~;

~~fixing~~providing circuit elements on the conductive plating layer ~~on respective mounting portions of desired conductive patterns~~;

~~commonly molding~~providing an insulating resin to cover collectively the circuit elements ~~on respective mounting portions~~ and to fill the isolation trenches;

forming conducive patterns by removing the conductive foil from opposite to the side where the circuit elements are provided until the insulating resin in the trenches is exposed ~~having thickness portions in which the isolation trenches are not provided~~; and

dicing the insulating resin appropriately to separate the circuit elements~~separating the insulating resin into respective mounting portions by dicing~~.

2. (Currently Amended) The circuit device manufacturing method according to claim 1, further comprising ~~the step of~~:

~~forming connecting member that connect~~ electrically connecting electrodes of the circuit elements ~~on respective mounting portions and desired~~ to the conductive foil~~patterns,~~ before ~~the step of commonly molding an~~ providing the insulating resin.

3. The circuit device manufacturing method according to claim 1, wherein the conductive foil is formed of any one of copper, aluminum, and iron-nickel.

4. (Currently Amended) The circuit device manufacturing method according to claim 1, wherein the conductive plating layer partially covers ~~is formed smaller than~~ the conductive foil~~patterns~~.

5. The circuit device manufacturing method according to claim 4, wherein the conductive plating layer is formed by gold or silver plating.

6. The circuit device manufacturing method according to claim 1, wherein the isolation trenches formed selectively on the conductive foil are formed by chemical or physical etching.

7. The circuit device manufacturing method according to claim 1, wherein at least one of bare semiconductor chips and chip circuit components are fixed as the circuit elements.

8. The circuit device manufacturing method according to claim 2, wherein the connecting member is formed by wire bonding.

9. (Currently Amended) The circuit device manufacturing method according to claim 8, wherein the wire bonding is applied onto the conductive plating layer ~~of the conductive patterns~~.

10. (Currently Amended) The circuit device manufacturing method according to claim 8, wherein a position ~~recognition~~ of the wire bonding is ~~executed~~ determined by ~~using contrasts~~contrasting between a region of the conductive foil without the conductive plating ~~patterns~~ and a region of the conductive plating layer on the conductive foil.

11. (Currently Amended) The circuit device manufacturing method according to claim 1, wherein the insulating resin is ~~covered~~provided by transfer molding.

12, (Currently Amended) The circuit device manufacturing method according to claim 1, wherein

~~a plurality of blocks in which conductive patterns on which at least a number of mounting portions of~~ the circuit elements are ~~formed are~~ provided in blocks which are aligned in ~~a~~ matrix fashion ~~are arranged~~ on the conductive foil.

13. (Currently Amended) The circuit device manufacturing method according to claim 12, wherein the insulating resin is ~~covered~~ provided by transfer molding for every block.

14. (Currently Amended) The circuit device manufacturing method according to claim 12, wherein the insulating resin is ~~separated into respective mounting portions by dicing every molded~~ diced to separate the blocks.

15. (Currently Amended) The circuit device manufacturing method according to claim 14, wherein the dicing is carried out by using alignment marks ~~formed together with the conductive patterns~~provided at a periphery of each block.

16. (Currently Amended) The circuit device manufacturing method according to claim 14, wherein the dicing is carried out by using opposing alignment marks ~~formed together with the conductive patterns~~provided at a periphery of each block.

17. (New) A circuit device manufacturing method according to claim 1, further comprising:

after providing the trenches in the conductive foil, covering the conductive foil including surfaces of the isolation trenches with a resist layer.

18. (New) A circuit device manufacturing method according to claim 17, further comprising:

after covering the conductive foil with the resist layer, selectively removing the resist layer on the conductive foil.

19. (New) A circuit device manufacturing method according to claim 18, further comprising:

providing the conductive plating layer where the resist layer has been selectively removed.